

### General Description

The 100N03 is N-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the synchronous buck converter applications.

### Features

- Simple Drive Requirement
- Fast Switching
- Low On-Resistance

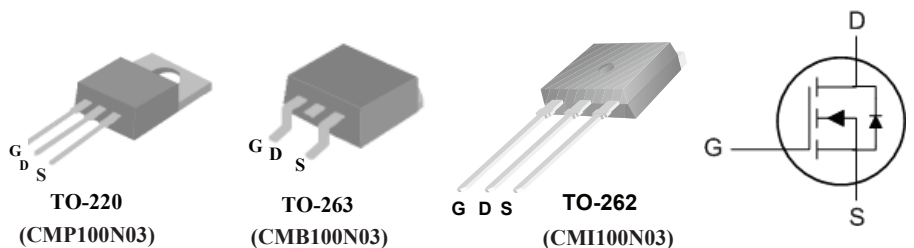
### Product Summary

BVDSS	R <sub>DS(on)</sub>	I <sub>D</sub>
30V	< 4mΩ	100A

### Applications

- HIGH CURRENT, HIGH SPEED SWITCHING
- DC-DC & DC-AC CONVERTERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- SOLENOID AND RELAY DRIVERS
- AUTOMOTIVE ENVIRONMENT

### TO220 / TO263 / TO262 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current <sup>1</sup>	100	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current <sup>1</sup>	56	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	320	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	600	mJ
I <sub>AS</sub>	Avalanche Current	56	A
P <sub>D</sub>	Total Power Dissipation	210	W
T <sub>STG</sub>	Storage Temperature Range	-65 to 175	°C
T <sub>J</sub>	Operating Junction Temperature Range	-65 to 175	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	62.5	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case	---	0.7	°C/W

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.035	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=40A$	2.7	3	3.8	m $\Omega$
		$V_{GS}=4.5V, I_D=40A$	---	4	5.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1	---	3	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=30V, V_{GS}=0V$	---	---	1	$\mu A$
		$V_{DS}=30V, V_{GS}=0V, TC=125^\circ\text{C}$	---	---	10	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}>I_{D(on)} \times R_{DS(on)max}, I_D=15A$	---	50	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	---	4.7	$\Omega$
$Q_g$	Total Gate Charge	$I_D=100A$	---	84	114	nC
$Q_{gs}$	Gate-Source Charge	$V_{DD}=24V$	---	21	---	
$Q_{gd}$	Gate-Drain Charge	$V_{GS}=4.5V$	---	36	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V$	---	40	---	ns
$T_r$	Rise Time	$I_D=40A$	---	112	---	
$T_{d(off)}$	Turn-Off Delay Time	$R_G=4.7\Omega$	---	144	---	
$T_f$	Fall Time	$V_{GS}=4.5V$	---	85	---	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	---	4900	pF
$C_{oss}$	Output Capacitance		---	---	1300	
$C_{rss}$	Reverse Transfer Capacitance		---	---	490	

### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1</sup>	$V_G=V_D=0V$ , Force Current	---	---	100	A
$I_{SM}$	Pulsed Source Current <sup>2</sup>		---	---	320	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=100A, T_J=25^\circ\text{C}$	---	---	1.5	V

Note :

1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$

3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=56A$